

05-11-2006

S. DEPARTMENT OF COMMERCE  
U.S. Patent and Trademark Office

Attorney Docket No. 520.46047X00

To the Honorable Commissioner of Patents

1. Name of conveying party(ies):

Shohci HATA  
Naoki MATSUSHIMA  
Takeru FUJINAGA

2. Name and address of receiving party(ies)

Name: **Hitachi Kyowa Engineering Co., Ltd.**

Street Address: **10-2, Benten-cho 3-chome, Hitachi-shi,  
IBARAKI, JAPAN**

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/ Execution Date: **3/3/06; 3/3/06;  
3/3/06.**

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other .

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

11/378,450

B. Patent Registration No.(s)

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **ANTONELLI, TERRY, STOUT & KRAUS, LLP**

Internal Address:

**1300 NORTH 17<sup>TH</sup> STREET - SUITE 1800**

City: **ARLINGTON** State: **VA** Zip **22209**

Phone Number: **(703) 312-6600**

Facsimile Number: **(703) 312-6666**

Email Address: **email@antonelli.com**

6. Total number of applications and patents involved **1**

7. Total fee (37 CFR 3.41)..... **\$40.00**

- ☒ Authorized to be charged by credit card  
☐ Authorized to be charged to deposit account  
☒ Enclosed  
☐ None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 numbers: **1040**  
Expiration date: **06/06**

b. Deposit account number: **01-2135**

Authorized User Name: **Donald E. Stout**

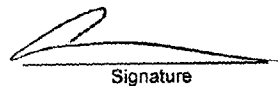
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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

**Alan E. Schiavelli, Reg#32,087**

Name of Person Signing

  
Signature

**05/09/2006 MBEYENE1 00000034 11378450**

**02 FC:0021 05/05/06**

Date

Total number of pages including cover sheet, attachments, and document: **2**

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, VA 22313-1450

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I, the undersigned, do hereby agree to sign and execute any further documents or instruments which may be necessary, proper in the prosecution of the above-named application or in the preparation and prosecution of any continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, interference proceedings, or otherwise to secure the title thereto in said assignee;

I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent when granted, to be held and enjoyed by said Hitachi Kyowa Engineering Co., Ltd.

INVENTOR(S)  
(明者フルネームサイン)

Hata

... further documents or instruments which may be necessary for the full end of term for which said invention was made and Hitachi Kyokai, Inc. has been held and enjoyed by me or my assigns.

I, the undersigned, do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said assignee, without examination, provisional, renewal, reviewed or reissue applications or in any amendment or otherwise to secure the title thereto in said assignee;

Signed on the date(s) indicated aside signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Hei Hata

Matsushita

INVENTOR(S)  
(発明者フルネームサイン)  
4

Date Signed  
(署名日)

ate Signed  
(署名日)

Mar. 3, 2006

Mar. 3, 2006

Mar. 3, 2006

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Mar. 3, 2006  
Mar. 3, 2006

Mar. 3, 2006

# ASSIGNMENT

## ( 議 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Kyowa Engineering Co., Ltd, a corporation organized under the laws of Japan, located at 10-2, Benten-cho 3-chome, Hitachi-shi, IBARAKI, JAPAN, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kyowa Engineering Co., Ltd. its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kyowa Engineering Co., Ltd. its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kyowa Engineering Co., Ltd.

**Signed on the date(s) indicated aside signatures:**

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1)	Shohei Hata	Mar. 3. 2006
2)	Naoaki Matsushima	Mar. 3, 2006
3)	Takemasa Fujinaga	Mar. 3, 2006
4)		
5)		
6)		
7)		
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